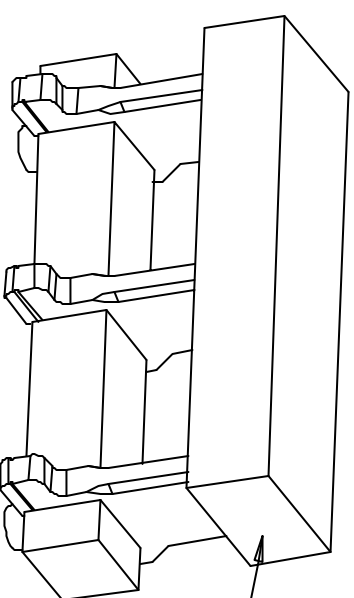
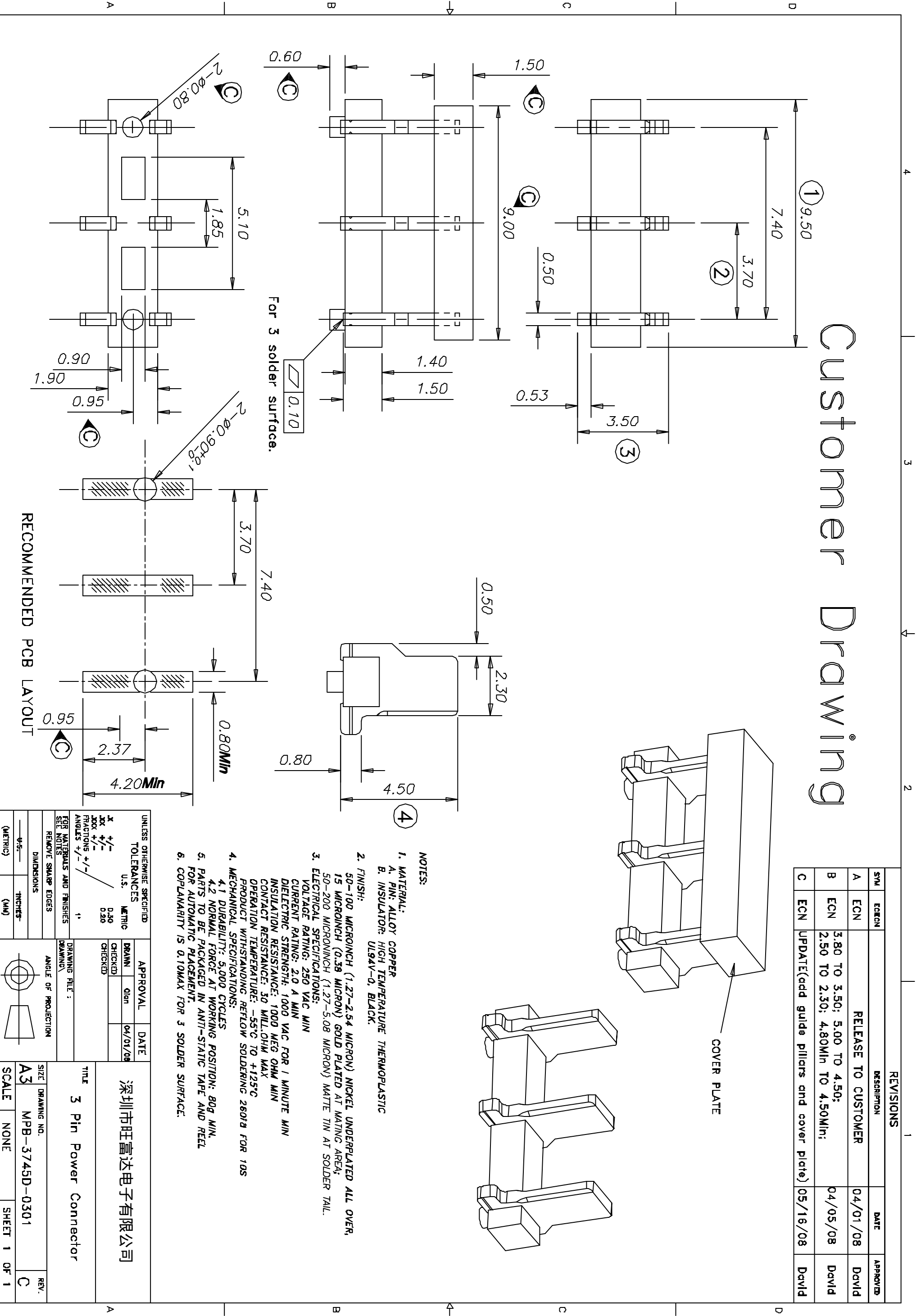
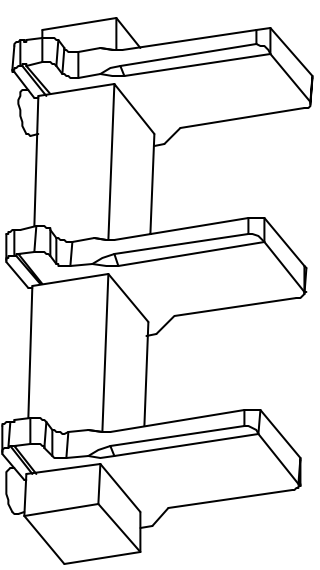


# Customer Drawing

REVISIONS			DATE	APPROVED
SYM	ECN	DESCRIPTION	DATE	APPROVED
A	ECN	RELEASE TO CUSTOMER	04/01/08	David
B	ECN	3.80 TO 3.50; 5.00 TO 4.50; 2.50 TO 2.30; 4.80Min TO 4.50Min;	04/05/08	David
C	ECN	UPDATE(add guide pillars and cover plate)	05/16/08	David



COVER PLATE



- NOTES:
1. MATERIAL:  
A. PIN: ALLOY COPPER  
B. INSULATOR: HIGH TEMPERATURE THERMOPLASTIC  
UL94V-0, BLACK.
  2. FINISH:  
50-100 MICRON (1.27-2.54 MICRON) NICKEL UNDERPLATED ALL OVER,  
15 MICRON (0.38 MICRON) GOLD PLATED AT MATING AREA;  
50-200 MICRON (1.27-5.08 MICRON) MATTE TIN AT SOLDER TAIL.
  3. ELECTRICAL SPECIFICATIONS:  
VOLTAGE RATING: 250 VAC MIN  
CURRENT RATING: 2.0 A MIN  
DIELECTRIC STRENGTH: 1000 VAC FOR 1 MINUTE MIN  
INSULATION RESISTANCE: 1000 MEG OHM MIN  
CONTACT RESISTANCE: 30 MILLIOHM MAX  
OPERATION TEMPERATURE: -55°C TO +125°C  
PRODUCT WITHSTANDING REFLOW SOLDERING 280°F FOR 10S
  4. MECHANICAL SPECIFICATIONS:  
4.1 DURABILITY: 5,000 CYCLES  
4.2 NORMAL FORCE AT WORKING POSITION: 80g MIN.  
PARTS TO BE PACKAGED IN ANTI-STATIC TAPE AND REEL  
FOR AUTOMATIC PLACEMENT.  
6. COPLANARITY IS 0.10MAX FOR 3 SOLDER SURFACE.

UNLESS OTHERWISE SPECIFIED		APPROVAL		DATE	
TOLERANCES	U.S.	DRAWN	QION	04/01/08	
	METRIC	CHECKED			
XX +/-	0.30				
XXX +/-	0.20				
FRACTIONS +/-					
ANGLES +/-	1°				

FOR MATERIALS AND FINISHES		DRAWING FILE :		TITLE	
REMOVE SHARP EDGES		ANGLE OF PROJECTION		3 Pin Power Connector	
DIMENSIONS				深圳市旺富达电子有限公司	
U.S. - INCHES				SIZE	DRAWING NO.
(METRIC)	(MM)			A3	MPB-3745D-0301
				SCALE	NONE
					SHEET 1 OF 1
				REV.	C